

2-PART SILICONE GAP FILLER TDG-Z10-SI-2C HALA

dispensable / 2 parts / Form-in-Place

TDG-Z10-SI-2C is a 2-part dispensable silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact.



Stand 07 / 2025

PROPERTIES

- ☐ Dispensable 2-part silicone
- ☐ Thermal conductivity: 10.0 W/mK
- ☐ Remains elastic after polymerisation
- ☐ Zero stress on components
- ☐ Heat accelerated curing
- ☐ Shock absorbing

AVAILABILITY

- ☐ Cartridges 2 x 25 ml / 2 x 200 ml / 2 x 600 ml
- ☐ Pail 2 x 25 kg

APPLICATION EXAMPLES

Thermal link of:

- ☐ FPBGA
- ☐ Capacitors
- ☐ Heat Pipes
- ☐ BGA

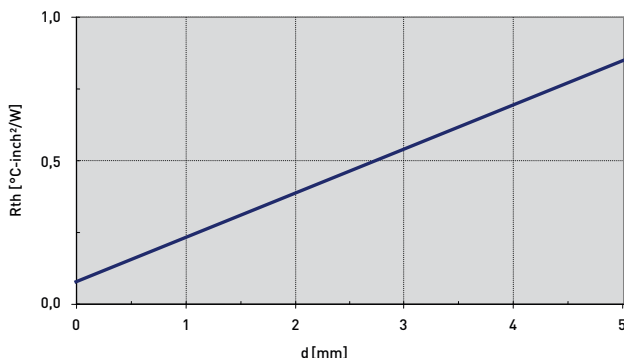
For use in Automotive applications
/ Telecommunication / Multimedia / Industrial PCs

Technisches Datenblatt

PROPERTY	UNIT	A PART	B PART
MATERIAL		Silicone	Silicone
Colour		Greenish Grey	Grey
Density @ 25 °C	g/cm ³	3.30	3.30
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	50	50
Viscosity	Pas	180	160
Viscosity (mixed)	Pas	170	170
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	Minutes	30 – 80	30 – 80
Curing Time @ 25 °C / 80 °C	Hours / Minutes	10 ± 2 / ≥ 30	10 ± 2 / ≥ 30
Shelf Life (from Date of Manufacturing, unopened, dry storage conditions @ -15 – 35 °C)	Months	9	9
Flammability (Equivalent)	UL 94	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ¹	W/mK	10	10
Operating Temperature	°C	- 40 to + 150	- 40 to + 150
Dielectric Strength	kV/mm	≥ 7	≥ 7
Volume Resistivity	Ohm - cm	≥ 1 x 10 ¹²	≥ 1 x 10 ¹²

Measurement technique according to: ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Warning: Only A / B part of the same lot number may be processed together.



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